

Composition Table

Product(Pb-free): XC6203xxxxFR-G
Typical mass: 130 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS No.
Silicon chip	0.5534	Silicon	4257	7440-21-3
	-	Arsenic	< 1	7440-38-2
Leadframe	48.3703	Copper	372079	7440-50-8
	0.0536	Iron	412	7439-89-6
	0.0170	Phosphorus	131	7723-14-0
	0.4777	Silver	3675	7440-22-4
Die attach	0.0791	Silver	608	7440-22-4
	0.0070	Epoxy resin	53	—
	0.0042	Acryl resin	33	—
	0.0027	Polybutadiene derivative	21	—
Bonding wire	0.0696	Gold	535	7440-57-5
Resin	68.4511	Silica	526547	60676-86-0
	5.4682	Epoxy resin	42063	—
	4.1762	Phenol resin	32125	—
Plating	2.2700	Tin	17462	7440-31-5

- * The component composition is based on the information provided by raw material vender.
- * The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.
- * Any indication [-] in CAS number means [confidential].